

A Windows/Linux Embedded Single Board Computer with XMC IO Site and 1 GbE Link

V1.5

FEATURES

- Combines an industry standard COM Express CPU module with XMC IO module in a compact, stand-alone design
- Powerful performance using Intel-based CPU core on a Type 10 mini size COM Express module
- Very small form factor: 150 x 75 mm
- Rugged, stand-alone operation
- Able to operate headless
- Runs Windows or Linux applications including RTOS variants
- Configurable IO uses standard XMC IO modules. Add anything from RF receivers to industrial control modules.
- PCI Express IO site (VITA 42.3) delivers up to 1600 MB/s to CPU memory
- Supports ISI XMC module features for private data channels, triggering and timing
- USB 3.0/2.0 x2, USB 2.0 x2 (internal), mini DisplayPort; 1 Gb Ethernet; Two Internal Generic Serial Ports
- PCI Express 1x4 (Gen 2) configuration for XMC interface
- Storage: 2 internal mSATA slots
- On-board XMC FPGA JTAG programmer
- Flexible 6V 14V DC operation

APPLICATIONS

- Embedded instrumentation
- Remote autonomous IO
- Mobile instrumentation
- Sensor data processing
- Distributed data acquisition



DESCRIPTION

The SBC-Nano is a customizable, turnkey embedded instrument that includes a full Windows/Linux PC and supports a wide assortment of ultimate-performance XMC modules. With its modular IO, scalable performance, and easy to use PC architecture, the SBC-Nano reduces time-to-market while providing the performance you need.

Distributed Data Acquisition – Put the SBC-Nano at the data source and reduce system errors and complexity.

Limitless flexibility – Different functionality can be achived by simply replacing the XMC module.

Uniquely customizable - XMC site for IO, user-programmable FPGA for IO interfaces, triggering and timing control, USB ports.

Remote or Local Operation - Continuous data streaming up to 500 MB/s (local SSDs) or 1 Gb/s Ethernet.

Rugged – Runs from the mSATA SSD drive in a compact, rugged 150 x 75 mm footprint that is ready for embedded operation.

Two Generic Serial Ports for system extension.

On-board JTAG programmer allows XMC module FPGA insystem programming directly from the Xilinx development tools.

6V -14V DC Operation - Perfect for portable or automotive battery-operated data loggers or waveform generators.

Xilinx Cool-Runner CPLD based System voltage and temperature monitor for safe operation.



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ORDERING INFORMATION

| Product | Part Number | Description |
|-------------------------------------|--|--|
| SBC-NANO x4 PCIE x1 Gbe | 90654-0-L0 90659-0-L0 | SBC-NANO x4 PCIE 1 Gbe DEV KIT XA/X6* SBC-NANO x4 PCIE 1 Gbe DEV KIT X3** |
| | | Kits Include: SBC-NANO WINDOWS/LINUX SINGLE-BOARD COMPUTER (SBC-Nano Carrier) COM EXPRESS MINI TYPE 10 MODULE INTEL x7-E3950 ATOM PROCESSOR 8GB DDR3L INDUSTRIAL TEMP SBC-NANO EXTENSION BOARD x2 mSATA capability x16 DIO x2 INTERNAL USB x2 INTERNAL SERIAL PORT FANSINK ASSEMBLY QUAD FAN CHASSIS, HEATSINKS, CONDUCTIVE COOLING to CHASSIS AND OTHER REQUIRED HARDWARE AC-DC POWER ADAPTER, USA Plug |
| Operating System | 2222210110 2222210113 | WIN 10 x64 PRO CENTOS 7 X64 |
| SOLID STATE DRIVES (mSATA)*** | 2226003444 2226013150 2226003445 | SAMSUNG 850 EVO MSATA 250GB SATA III SAMSUNG MEM MSATA 860 EVO 500GB SATA III SAMSUNG 850 EVO MSATA 1TB MINI-SATA III |
| XMC MODULES | | Consult Sales for ISI XMC MODULE listing (<u>InnovativeSales@Molex.com</u>) |
| DIO BREAKOUT | 80365-0-L0 2226003475 | DIO 2X13 TWINAX BREAKOUT BOARD NO CABLE ASSY CABLE DIO 2X13 TWINAX W/ LATCH 36" |

Notes: 1. Use with ISI XA or X6 Series XMC Modules.

2. Use with ISI X3 Series XMC Modules.



3. System can accommodate two mSATA SSDs; one is required for OS and other software storage and must be always installed, second is optional.

Consult sales if other options (SBC-Nano Electronics Stack only / no chassis, conduction cooling without fansink, ruggedized versions, eMMC etc.) are desired.

BLOCK DIAGRAM

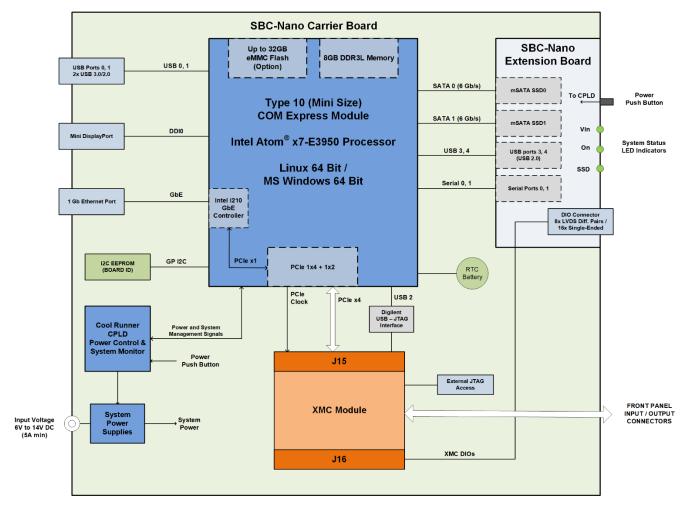


Figure 1. SBC-Nano System Simplified Block Diagram





Figure 2. Front view of SBC-Nano system in a chassis with XMC module installed. Fansink (on the top) can be substituted with a coldplate in conduction-cooled applications.



Figure 3. Rear view of SBC-Nano system in a chassis.



Figure 4. Front isometric view of SBC-Nano system in a chassis.



Figure 5. Rear isometric view of SBC-Nano system in a chassis.

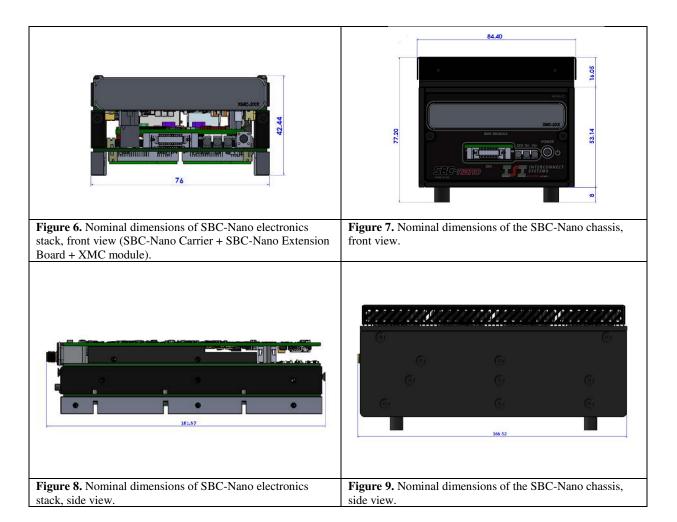


Figure 6. Top view of SBC-Nano electronics stack: XMC module (X6-400M module is shown), SBC-Nano Carrier Board and SBC-Nano Extension Board.



Figure 7. Bottom view of SBC-Nano electronics stack.





Standard Features

| COM Express Site | | | |
|------------------|---|--|--|
| | PCIMG Com Express® Module | | |
| Standards | Base Specification COM.0 R2.1 | | |
| | Compliant | | |
| Type | 10 | | |
| | Supports 84 x 55 mm modules | | |
| Size | (mini size) | | |
| | COMe-mAL10 E2 E3950 8E | | |
| Verified Modules | (Kontron) | | |
| | nanoX-AL-E3950-8G (Adlink) | | |
| CDLLT | Intel® Atom TM x7-E3950, 4C, 1.6 / | | |
| CPU Type | 2.0 GHz, 12 W TDP | | |
| COM Express | 8 GByte Dual Channel DDR3L- | | |
| Memory | 1866 (-1600) memory down | | |

| Timing and Triggering Support Features | | | |
|--|---------------------------------|--|--|
| Clock and Trigger | XMC Module dependent | | |
| Power Requirements | | | |
| Input Voltage | 6V DC to 14V DC; 12V DC Nominal | | |
| Power | Varies according to XMC and COM | | |
| Consumption | Express module requirements | | |
| | 30W to 40W typical | | |
| | <15W with standard COM Express | | |
| | module excluding XMC | | |
| Power Input | 36V / 10A DC Power Jack; | | |
| Connector | 2.5mm x 5.5mm | | |
| Power and Thermal Management | | | |



| MMC (d' 1) | 22 CD (1 1F) 1 | | | | |
|----------------------------|---|--|--|--|--|
| eMMC (optional) | 32 GByte on-board Flash | | | | |
| IO Ports | T | | | | |
| USB | 2x USB 3.0 (incl. USB 2.0) Type A Rear Panel Ports (USB 0, USB 1) 2x USB 2.0 Internal Headers (USB 3, USB 4) | | | | |
| Video | Mini DipsplayPort (Rear Panel Port) | | | | |
| Ethernet | Single 10/100/1000 Mb/s Port (J45 on Rear Panel) | | | | |
| SATA | 2x SATA 6 Gb/s internal ports (mSATA) | | | | |
| Serial | 2x 2 UART ports COM 0, COM 1 (TX/RX only) | | | | |
| XMC Sites | | | | | |
| Module Sites | 1 | | | | |
| Standards | ANSI/VITA 42.0-2016 XMC: Switched Mezzanine Card Base Specification ANSI/VITA 42.3-2014 XMC: PCI Express Protocol Layer ANSI/VITA 20-2005 (S2018) Conduction cooled PMC | | | | |
| PCI Express Connections | XMC Site: 4 Lanes Gen 2 | | | | |
| J16 Support | 16 single/8 differential direct connections to Front Panel DIO connector | | | | |
| XMC Power | | | | | |
| VPWR | 12V +/-5%; 4A max (with supplied AC-DC Adapter) | | | | |
| 3.3V | 3.3V +/-3%; 6A max | | | | |
| 3.3VAUX | 3.3V +/-3%; 0.5A max | | | | |

| T | | |
|--|--|--|
| Low power states supported including | | |
| wake features from PCI Express and | | |
| LAN | | |
| System will not power up or the | | |
| power will be shut down with the | | |
| input voltage outside of the 6V to 14V | | |
| range | | |
| Separate Temperature Monitors on | | |
| COM Express Module and | | |
| XMC | | |
| Software programmable warning and | | |
| failure levels | | |
| Failure level alarm disables power | | |
| | | |
| Power sequencing; power good | | |
| indication | | |
| Forced Air (Fansink)* | | |
| | | |
| 165 x 85 x 85 mm | | |
| 1,150g typical (SBC-Nano Carrier + | | |
| SBC-Nano Extension + mSATA SSD | | |
| (1) + X6-1000M in a chassis with | | |
| Fansink) | | |
| Lead-free / RoHS compliant | | |
| _ | | |
| 17,000 Hours | | |
| pter | | |
| 90 – 264 V AC; 50/60Hz | | |
| 12V DC | | |
| 8.33A | | |
| 136 x 58.5 x 33.7mm (W x H x D) | | |
| | | |
| 0°C to + 50°C, non-condensing ** | | |
| | | |
| | | |

Notes: 1. Contact Sales if conduction cooling option is desired.

2. Standard (-L0) option. Contact Sales if other options are required.

ABSOLUTE MAXIMUM RATINGS

Exposure to conditions exceeding these ratings may cause system damage!

| Parameter | Min | Max | Units | Conditions |
|-----------------------------|-----|------|-------|--|
| Input Supply Voltage (Vin)* | 6.0 | 14.0 | V | Recommended input supply voltage is 12V. |
| Operating Temperature | 0 | +70 | °C | Non-condensing, with forced air cooling |
| Storage Temperature | -40 | +100 | °C | |



| ESD Rating | - | 2,000 | V | Human Body Model |
|------------|---|-------|--------|--|
| Vibration | - | 5 | g | 9-200 Hz, Class 3.3 per ETSI EN 300 019- 1-3 V2.1.2 (2003-04) |
| Shock | - | 40 | g peak | Class 3.3 per ETSI EN 300 019-1-3 V2.1.2 (2003-04) |

^{*} SBC-Nano designed to withstand input voltage up to 20V without damage, but it would not get powered-up.

Input voltage must never exceed 20V or connected in reversed polarity – this will cause the system damage!

Operating Environment Ratings

The SBC-Nano can be used in a variety of applications with different operating environment temperature, shock and vibration levels. Contact Sales for available Ruggedization Levels.

Architecture and Features

The SBC-Nano combines a Windows/Linux compatible embedded PC with XMC IO module and supporting peripherals to create a customizable instrument for a wide variety of applications.

Embedded PC

The embedded PC architecture is Windows/Linux compatible – it runs the same applications as a desktop computer. The COM Express CPU module is a PC on a module and provides the computing engine, available with four low power Atom cores for ultimate computing power.

The COM Express module provides the PCI Express bus that links the XMC module to the CPU. The XMC module behaves identically to PCI Express add-in cards within a PC and are software compatible with PC applications. The

COM Express Advantages

- Intel compatible PC runs Windows and Linux software
- Scalable performance
- Latest technologies: PCIe gen2, Gb Ethernet, USB 3.0
- Upgradeable as requirements change and evolve
- Tech refresh every 18 months
- Ultra-Compact 84 x 55 mm form-factor (Type 10)
- Industry-standard, multi-vendor

PCI Express bus tightly couples the CPU to the XMC modules and outperforms previous generation systems by 2 to 4 times. In the SBC-Nano architecture, the XMC module linked to CPU with 4 lane PCIe bus at Gen 2 speed providing data transfer rates between the XMC module and CPU at speed up to 1600 MB/s.

SBC-Nano provides familiar PC interfaces for expansion and connectivity: Ethernet, USB ports, and SATA SSD. Multiple SBC-Nano's may be connected into a mesh using the 1 Gb Ethernet port for high performance IO supporting up to ~100 MB/s transfer rates to external devices such as other eInstruments.

The mini DisplayPort video port and USB keyboard/mouse make operating the SBC-Nano to operate just like any PC. Standard PC screens with up to 4K resolution are supported. "Headless" operation is also supported for truly embedded applications without keyboard/monitor/mouse attached. In the headless mode, the SBC-Nano can be remotely controlled and accessed over Ethernet or via remote protocols such as RDP or VNC.



XMC IO Site

A single XMC module site enables the SBC-Nano to be configured with a wide variety of IO modules. The XMC site is for PCI Express mezzanine cards conforming to ANSI/VITA 42.3 standard, which are 75 x 150 mm size modules (IEEE 1386). Each installed module must employ a suitable heat spreader to conduct heat to the thermal rails running on the long edge of the SBC-Nano carrier and connected to a coldplate within the system.

XMC Modules for IO

- Flexible, modular IO
- Industry-standard ANSI/VITA 42.3
- PCI Express with up to 1.6 GB/s transfer rates
- XU, XA, X6 and X3 module Families available from ISI
- Industry-standard, multi-vendor

XMC Modules

SBC-Nano makes is easy to build your custom, turnkey embedded instrument by simply adding an XMC module with desired functionality. ISI offers an array of high-performance PCI Express XMC modules to create your own solution.

ISI XMC module families feature analog and digital IO with FPGA computing cores on high performance PCI Express modules and offered in XU, XA, X6 and X3 families. The XU family features Xilinx Kintex Ultrascale FPGA, the XA - Xilinx Artix-7, the X6 - Xilinx Virtex 6 and the X3 - Xilinx Spartan 3. ISI's Velocia architecture data packet system allows these modules to stream data continuously to system memory at rates up to 1.6 GB/s – making the SBC-Nano well suited for data logging and playback functions.

SBC-Nano supports ISI XMC module families' special features for sampling, triggering, and controls. Each XMC module's J16 interface also routes 8 differential/16 single ended connections to a high-speed DIO connector for custom applications.

A list of all currently available XMC modules can be found on the ISI website here. Software and Logic tools are available for all ISI XMC Modules. Please refer to used XMC module's documentation for additional details, including ordering information, pricing and conditions; contact Sales if more information is required.

Triggering and Sample Clocks

Sample clocks for the XMC modules can be generated using an XMC module's on-card PLL or from an external clock input. The PLL can use the external clock input as a reference.

Triggering on XMC modules can be done via the software or by using the external trigger signal. More details on the clock and triggering features can be found in used XMC module's specifications.

Remote Operation

SBC-Nano can be operated using Ethernet as a remote computer or embedded instrument. For pure embedded operation, the SBC-Nano can operate "headless" without monitor, keyboard or mouse. The system can be configured to boot from an optional 32 GB eMMC flash drive located on the COM Express module itself. Thus, the two SATA links and bandwidth can be dedicated to storage of application-specific data.



XMC Module FPGA Configuration

The SBC-Nano has a built-in USB-JTAG Interface circuitry which allows convenient loading of the FPGA application image directly from the Xilinx Vivado or Impact development tools without the external USB JTAG programming hardware such as Xilinx Platform Cable USB and disassembling the SBC-Nano system. This helps significantly accelerate FPGA custom logic development. Please note that the XMC module must support JTAG programming via the J15 connector to be able to use this feature.

DIO SIGNAL CONNECTIONS

The following table and pictures show the DIO Signals available on the SBC-Nano front panel DIO connector. DIO signals are routed from the FPGA on XMC module internally all the way to the SBC-Nano DIO connector as impedance controlled 100 Ohms differential / 50 Ohms single ended traces to maintain best signal integrity. It is recommended to use LVDS signaling from FPGA with proper termination on receiving end whenever possible for best possible performance. For the XMC FPGA DIO signal mapping please refer to the specific XMC module's documentation. A special high performance / high speed DIO cable and a breakout board with SMA connectors (available from ISI) provide user with convenient way to access DIO signals (see ordering section of this document for more information).

| DIO SIGNAL | Front Panel DIO Connector |
|---------------|------------------------------------|
| DIO_0_P | 3 |
| DIO_0_N | 5 |
| DIO_2_P | 15 |
| DIO_2_N | 17 |
| DIO_4_P | 4 |
| DIO_4_N | 6 |
| DIO_6_P | 16 |
| DIO_6_N | 18 |
| DIO_1_P | 9 |
| DIO_1_N | 11 |
| DIO_3_P | 21 |
| DIO_3_N | 23 |
| DIO_5_P | 10 |
| DIO_5_N | 12 |
| DIO_7_P | 22 |
| DIO_7_N | 24 |
| Signal Ground | 1, 2, 7, 8, 13, 14, 19, 20, 25, 26 |





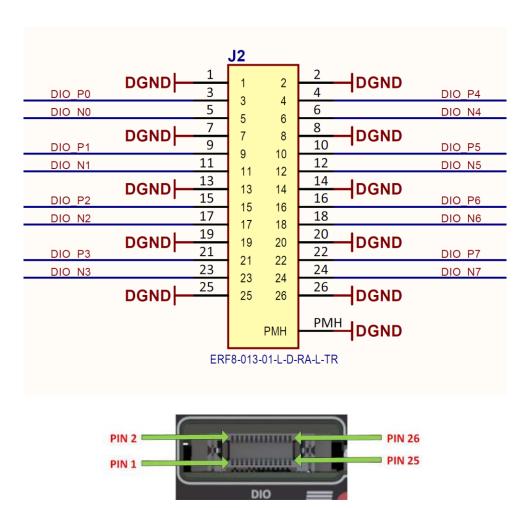


Figure 10. Front Panel DIO Connector Signals



Usage and Market

The SBC-Nano is a digital device and apparatus exclusively for use in business, industrial and commercial environments. The SBC-Nano is not marketed, sold or otherwise made available for home or residential environment use.

The SBC-Nano is exclusively for use with wired input and output signals. The SBC-Nano is not an intentional radio transmitter or receiver and is not marketed, sold or otherwise made available for connection to wireless media (with an antenna, etc.).

The SBC-Nano is not a "PC" ("personal" or "portable computer" marketed for home or residential environment use) or "PC" peripheral and is not marketed, sold or otherwise made available as a "PC" or "PC" peripheral.

The SBC-Nano may be sold as a subassembly where the integrator/purchaser takes responsibility for their assembled digital device's or apparatus's compliance. Consult ISI/Molex for clarification and assistance.



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